MP5424

5V PMIC with Four 4.5A/2.5A/4.5A/2A Buck Converters, 3 LDOs, 1 Load Switch, and Flexible System Settings via I²C and MTP

DESCRIPTION

The MP5424 is a complete power management solution that integrates four high-efficiency stepdown DC/DC converters, three low-dropout (LDO) regulators, one load switch, and a flexible logic interface.

Constant-on-time (COT) control in the DC/DC converter provides fast transient response. The 1.1MHz default switching frequency (f_{SW}) during continuous conduction mode (CCM) greatly reduces the external inductance and capacitance. Full protection features include under-voltage lockout (UVLO) protection, overcurrent protection (OCP), over-voltage protection (OVP), and thermal shutdown.

The output voltage (V_{OUT}) can be adjusted via the I²C bus or preset by the multiple-time programmable (MTP) interface. The startup/shutdown sequence can also be configured via the MTP and controlled via the I²C bus.

The MP5424 requires a minimal number of external components, and is available in a small QFN-26 (3.5mmx4.5mm) package.

FEATURES

- **High-Efficiency Step-Down Converters:**
	- o Buck 1: 4.5A DC/DC Converter
	- o Buck 2: 2.5A DC/DC Converter
	- o Buck 3: 4.5A DC/DC Converter
	- o Buck 4: 2A DC/DC Converter
	- o Buck 1 and Buck 3 Can Work in Parallel
	- o Buck 2 and Buck 4 Can Work in Parallel
	- \circ 2.7V to 5.5V Operating V_{IN} Range
	- o Buck 1, Buck 2, and Buck 3 Selectable V_{OUT} Range: 0.4V to 2.2V/7.4mV Step or 0.4V to 3.58V V_{OUT} /12.5mV Step
	- \circ Buck 4 V_{OUT} Range: 0.4V to 3.58V V_{OUT}/12.5mV Step
	- \circ Adjustable Switching Frequency (f_{SW})
	- \circ Adjustable Soft-Start Time (t_{SS})
	- o Adjustable Phase Delay
	- o Configurable Forced PWM (FPWM) Mode or Auto-PFM/PWM Mode
	- o Output OCP and OVP
- **Low-Dropout (LDO) Regulators:**
	- o Three 300mA, Low-Noise LDOs
	- o Two Separate Input Power Supplies
	- o 50mV Dropout at 300mA Load
- **Load Switch:**
	- o 2.7V to 5.5V/3A Load Switch
	- o 50mΩ On Resistance at $V_{IN} = 5V$
	- \circ On/Off Control via the I²C and Programmable Sequence
	- o Configurable Output Discharge Function via the I ²C (Default: On)
- **System:**
	- Ω 1²C Bus and User-Programmable MTP
	- \circ Two-Time Programmable MTP (1)
	- o Start-Up/Shutdown Control
	- o Enable Pin (EN1) for Sleep Mode Entry and Recovery Control
	- o Start-Up Reset Output
	- o Flexible Start-Up/Shutdown Sequence via MTP (0.5ms, 2ms, 8ms, or 16ms Selectable Time Slot)
	- o Available in a QFN-26 (3.5mmx4.5mm) Package

WAPL Optimized Performance with MPS Inductor MPL-AL6050 **Series**

Note:

1) The two-time programmable MTP is only for the standard version of the MP5424GRM-0000.

APPLICATIONS

- General Consumer
- Camera Modules
- 3.3V/5V Powered Systems
- Space-Limited Systems

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TYPICAL APPLICATION

MTP-EFUSE SELECTED TABLE BY DEFAULT (MP5424GRM-0000)

Note:

2) The load switch supply is on the LSWI pin. The supply voltage range is between 2.7V and 5.5V.

ORDERING INFORMATION

* For Tape & Reel, add suffix -Z (e.g. MP5424GRM-0000-Z, MP5424GRM-xxxx-Z).

** "xxxx" is the configuration code identifier for the register setting stored in the MTP.

The default number is "0000". Each "x" can be a hexadecimal value between 0 and F. Contact an MPS FAE to create this unique number.

TOP MARKING

MPSYW M5424 LLLLL

MPS: MPS prefix Y: Year code W: Week code M5424: Part number LLLLL: Lot number

EVALUATION KIT EVKT-MP5424

EVKT-MP5424 kit contents (items below can be ordered separately):

Order direct from MonolithicPower.com or our distributors.

PIN FUNCTIONS

ABSOLUTE MAXIMUM RATINGS (3)

ESD Ratings (5) (6)

Recommended Operating Conditions (7)

Thermal Resistance θJA θJC

Notes:

- 3) Exceeding these ratings may damage the device.
- 4) The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-toambient thermal resistance θ_{JA} , and the ambient temperature TA. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J) (MAX) - T_A) / θ_{JA} . Exceeding the maximum allowable power dissipation can cause excessive die temperature, and the device may go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- 5) HBM is measured in accordance with JEDEC specification JESD22-A114. JEDEC document JEP155 states that a 500V HBM allows for safe manufacturing with a standard ESD control process.
- 6) CDM is measured in accordance with JEDEC specification JESD22-C101. JEDEC document JEP157 states that a 250V CDM allows for safe manufacturing with a standard ESD control process.
- 7) The device is not guaranteed to function outside of its operating conditions.
- 8) Measured on EV5424-R-00A, 4-layer PCB.
- 9) Measured on JESD51-7, 4-layer PCB. The values given in this table are only valid for comparison with other packages and cannot be used for design purposes.
- 10) These values were calculated in accordance with JESD51-7, and simulated on a specified JEDEC board. They do not represent the performance obtained in an actual application.

ELECTRICAL CHARACTERISTICS

 V_{IN1} = V_{IN2} = V_{IN3} = V_{IN4} = V_{IN5} = V_{AVIN} = 5V, T_J = -40°C to +125°C⁽¹¹⁾, typical values are tested at **TJ = 25°C, unless otherwise noted.** (12)

ELECTRICAL CHARACTERISTICS *(continued)*

 V_{IN1} = V_{IN2} = V_{IN3} = V_{IN4} = V_{IN5} = V_{AVIN} = 5V, T_J = -40°C to +125°C⁽¹¹⁾, typical values are tested at **TJ = 25°C, unless otherwise noted.** (12)

ELECTRICAL CHARACTERISTICS *(continued)*

 V_{IN1} = V_{IN2} = V_{IN3} = V_{IN4} = V_{IN5} = V_{AVIN} = 5V, T_J = -40°C to +125°C⁽¹¹⁾, typical values are tested at **TJ = 25°C, unless otherwise noted.** (12)

ELECTRICAL CHARACTERISTICS *(continued)*

 V_{IN1} = V_{IN2} = V_{IN3} = V_{IN4} = V_{IN5} = V_{AVIN} = 5V, T_J = -40°C to +125°C⁽¹¹⁾, typical values are tested at **TJ = 25°C, unless otherwise noted.** (12)

Notes:

11) Guaranteed by over-temperature correlation. Not tested in production.

12) Tested with default version (MP5424GRM-0000), unless otherwise noted.

13) Guaranteed by engineering sample characterization.

14) It is recommended to use I²C function after the start-up sequence is complete (e.g. all enabled power rails have completed start up). Figure 2 shows the I^2C timing diagram for reading the I^2C interface specifications.

I ²C TIMING DIAGRAM

Figure 2: I 2C Timing Diagram

TYPICAL CHARACTERISTICS

Performance waveforms are tested on the evaluation board, V_{IN} **= 5V,** T_A **= 25°C, tested using default spec parts, unless otherwise noted.**

TYPICAL CHARACTERISTICS *(continued)*

Performance waveforms are tested on the evaluation board, $V_{IN} = 5V$ **,** $T_A = 25^{\circ}C$ **, tested using default spec parts, unless otherwise noted.**

TYPICAL PERFORMANCE CHARACTERISTICS

Performance waveforms are tested on the evaluation board, $V_{IN} = 5V$ **,** $T_A = 25^{\circ}C$ **, tested using default spec parts, unless otherwise noted.**

Start-Up through PWRON

All LDO rails, no load, $V_{LSWI} = 3.3V$

Shutdown through PWRON

All LDO rails, no load, $V_{LSWI} = 3.3V$, all buck rails disabled

Start-Up through PWRON

TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

Performance waveforms are tested on the evaluation board, $V_{IN} = 5V$ **,** $T_A = 25^{\circ}C$ **, tested using default spec parts, unless otherwise noted.**

SCP Entry Buck 4 output = 1.35V, RSTO_MODE = 01

SCP Steady State Buck 4 output = $1.35V$, RSTO_MODE = 01

TYPICAL PERFORMANCE CHARACTERISTICS *(continued)*

Performance waveforms are tested on the evaluation board, $V_{IN} = 5V$ **,** $T_A = 25^{\circ}C$ **, tested using default spec parts, unless otherwise noted.**

Load Transient Response

FUNCTIONAL BLOCK DIAGRAM

Figure 3: Functional Block Diagram

OPERATION

The MP5424 provides a complete power management solution for 5V systems**,** such as televisions**.** It integrates four high-frequency, synchronous rectification, step-down switchmode converters, as well as three low-dropout (LDO) regulators and one load switch. The compact QFN-26 (3.5mmx4.5mm) package reduces component count and PCB space.

The default output voltage (V_{OUT}) , start-up sequence, and dynamic voltage scaling can be adjusted via the I^2C and multiple-time programmable (MTP) interfaces. The I²C also provides powerful logic functions. See the I²C Register Map section on page 35 for more details**.**

Figure 4: Power Control State Machine Diagram

Power Control

State Machine Description

The state machine has a number of status options, including no supply, shutdown, start-up sequence, start-up, shutdown sequence, configure MTP, and shutdown event (see Figure 4 on page 17). These statuses are described below.

No Supply

The PMIC's input pin (AVIN) has a UVLO detection circuit. If the input voltage (V_{AVIN}) drops below the under-voltage lockout (UVLO) rising threshold, then all of the PMIC's functions are disabled.

Shutdown

All of the power rails turn off, and the PMIC enters the shutdown state once V_{AVIN} drops below its UVLO falling threshold. In the shutdown state, the PMIC monitors the poweron factors. Once a power-on factor is detected, the device begins the start-up sequence.

Start-Up Sequence

The DC/DC converters, LDOs, and load switch turn on sequentially according to the order configured via the MTP e-fuse.

Start-Up

The DC/DC converters, LDOs and load switch turn on, and the RSTO pin's output goes high. In the start-up state, the PMIC monitors the poweroff factors and configure MTP factors.

Shutdown Sequence

If the PMIC detects the shutdown factors during a start-up state, then the PMIC enters the shutdown sequence. RSTO is pulled low. Then the DC/DC converters, LDOs, and load switch turn off sequentially according to the order configured via the MTP e-fuse.

MTP Configure

The buck converters, LDOs, and load switch turn off in the shutdown sequence when entering MTP mode. After MTP configuration is complete, the PMIC reloads the MTP to the I²C registers and monitors the power-on factors.

Shutdown Event

If the PMIC detects any of the following conditions, then it enters a no supply or

shutdown state, regardless of the current state.

- If the input voltage (V_{IN}) drops below the UVLO falling threshold, then the device enters a no supply state.
- If thermal shutdown is triggered, then the device enters a shutdown state.

Power-On Factor

The PMIC has several power-on factors, including PWR_ON, thermal recovery, and EN1. These factors are described below.

PWRON_ON

If the PWRON pin is pulled to logic high $(PWRON_MODE = 0)$ or there is a falling edge on the PWRON pin (PWRON MODE = 1), then the PMIC enters the start-up sequence. See the PWRON Functions section on page 21 for more details.

Thermal Recovery

If the die temperature exceeds the thermal shutdown threshold, then the PMIC enters the shutdown state. Once the die temperature drops below the threshold, the PMIC enters the startup sequence.

EN1

If the EN1 function is enabled, and EN1 is pulled high (EN1 INV defines EN1's active high) or EN1 is pulled low (EN1_INV defines EN1's active low), then the power rails controlled by EN1 enter the start-up sequence. See the EN1 Functions section on page 22 for more details.

Start-Up Sequence

There are 16 selectable time slots for the startup sequence. All of the DC/DC converters, LDOs, and load switch can be configured between 0 and 15 time slots by the MTP e-fuse. The delay time between each time slot can be adjusted via the MTP TIME_SLOT bits. The time does not change with the switching frequency (f_{SW}) .

RSTO goes high with the RSTO_DELAY time once the start-up sequence is complete. The DC/DC converter, LDOs, and load switch startup sequences are set by POWER_ON_SLOT_

NO and PWR_ON_TIME_SLOT_MODE. See the MTP E-Fuse Description on page 28 for more details.

Figure 5: Start-Up Sequence

Buck Regulators, LDOs, and Load Switch On

The MP5424 provides a configurable start-up sequence. See the MTP E-Fuse Configuration Table on page 26 for details on which bits set the time slot number for each channel.

Shutdown Factor

The PMIC shutdown factors are PWRON_OFF and EN1. They are described below.

PWRON_OFF

If the PWRON pin is pulled low (PWRON_MODE $= 0$) or if there is a falling edge on PWRON (PWRON $MODE = 1$), then the PMIC enters the shutdown sequence. See the PWRON Functions section on page 21 for more details.

EN1

If the EN1 function is enabled, and EN1 is pulled low (EN1_INV defines EN1 as active high) or EN1 is pulled high (EN1 INV defines EN1 as active low), then the power rails controlled by EN1 enter the shutdown sequence. See the EN1 Functions section on page 22 for more details.

Shutdown Sequence

There are 16 selectable time slots for the shutdown sequence. All of the DC/DC converters, LDOs, and load switch can be configured between 0 and 15 time slots by the MTP e-fuse. The delay time between each time slot can be adjusted via the MTP TIME_SLOT bits. The time does not change with f_{SW} .

RSTO is pulled low prior to when the DC/DC converters, LDOs, and load switch turn off. The DC/DC converter and LDO shutdown sequences are set by POWER_OFF_SLOT_NO and POWER_OFF_SLOT_MODE. See the MTP_E-Fuse Configuration Table on page 26 for more details.

Configurable MTP

Follow the steps below to configure the MTP efuse via the I²C interface:

- 1. Before configuring the e-fuse, ensure that all of the buck converters and LDOs have no load.
- 2. Write the correct MTP program password to register 0x26.
- 3. Set ENTER_MTP_MODE to 1 to enter MTP configure mode. All bucks and LDOs are turned off in this mode.
- 4. Write the desired content to the I^2C registers.
- 5. Set V_{IN1} and V_{AVIN} between 6.4V and 6.5V, with a minimum 150mA current capability.
- 6. Set PROGRAM_MTP to 1 to start the MTP e-fuse program.
- 7. The PMIC calculates the sum of all the related I²C registers to be burned to the MTP register. The checksum result is also written to the MTP register.
- 8. After the MTP write operation is complete (typically 100ms), the PMIC sets the PROGRAM MTP bit to 0, and the I^2C register write protection is unlocked. ENTER_MTP_MODE is also set to 0.
- 9. After MTP configuration, the PMIC reloads the MTP to the related I^2C registers and the PWRON pin function is re-enabled. Then the bucks, LDOs, and load switch then start-up based on their power-on factors. I²C communication is enabled after the start-up sequence is complete.
- 10. Decrease V_{IN1} and V_{AVIN} below 5.5V, then restart the power supply to resume normal operation.

Before loading the MTP data into the I²C register during a start-up through VIN, the PMIC does a checksum calculation for all of the related MTP registers, and compares the checksum calculation to the checksum byte. If they match, then the MTP data is loaded into the I^2C register. If they do not match, then the I^2C register uses the hard-coded default value. There is an 1^2C register flag bit to indicate a checksum error.

Shutdown Sequence

If the V_{INx} drops below its UVLO falling threshold

or if thermal shutdown is triggered, then the PMIC enters the shutdown sequence. All of the DC/DC converters, LDO regulators, and load switch turn off at the same time.

Figure 7: Shutdown Sequence

High-Efficiency Buck Converter

Buck 1, buck 2, buck 3, and buck 4 are synchronous, step-down DC/DC converters that have built-in UVLO protection, soft start (SS), compensation, and over-current protection (OCP) with hiccup mode. Constant-on-time (COT) control with fixed frequency provides fast transient response. The switching clock is phase-shifted from buck 1 to buck 4 during continuous conduction mode (CCM). All of the buck converters can support a 100% duty cycle.

Power Supply and Under-Voltage Lockout (UVLO) Protection

VIN1 is the power supply for buck 1. VIN2 is the power supply for buck 2, LDO2. VIN3 is the power supply for buck 3. VIN4 is the power supply for buck 4. VIN5 is the power supply for LDO 4 and LDO 5. LSWI is the power supply for load switch. AVIN is the power input to bias the internal logic blocks.

VIN1, VIN2, VIN3, VIN4, VIN5, and AVIN have their own UVLO thresholds with hysteresis. Once V_{AVIN} exceeds its UVLO rising threshold, the PWRON logic is enabled and ready to accept start-up and shutdown commands.

Internal Soft Start (SS)

SS is implemented to prevent the PMIC V_{OUT} from overshooting during start-up. As the PMIC starts up, the internal circuitry of each power rail generates a soft-start voltage (V_{ss}) that ramps up from 0V. The soft-start time $(t_{\rm SS})$ lasts until $V_{\rm SS}$

exceeds the reference voltage (V_{REF}). Once V_{SS} exceeds V_{REF} , then V_{REF} takes over as the reference. The four buck outputs' t_{SS} are adjustable via the MTP. For the LDO2 through LDO5 outputs, t_{SS} is fixed internally at 50 μ s. For the load switch, the soft-start slew rate is consistent at 1.5mV/µs.

Output Discharge

In order to discharge the output capacitor (C_{OUT}) during the shutdown sequence, there is a passive discharge path from the DC/DC converter outputs, LDO outputs, and load switch output to ground. The discharge path turns on once the corresponding channel is disabled. The typical discharge resistance is Ω. The discharge function can be enabled or disabled through the I²C interface.

Over-Voltage Protection (OVP)

The MP5424 monitors the feedback voltage (V_{FB}) to detect possible over-voltage (OV) conditions. If V_{FB} exceeds 120% of the target voltage, then both the high-side MOSFET (HS-FET) and lowside MOSFET (LS-FET) turn off, and the discharge path is turned on. The part exits this regulation period once V_{FB} drops below 110% of VREF.

Over-Current Protection (OCP)

If the peak inductor current (I_L_{PEAK}) reaches its set limit and the HS-FET is on, then OCP is triggered. The LS-FET turns on until the inductor current (I_L) drops to the valley current limit

 $(I_{LIMIT\ VALUEY})$. Once I_L reaches $I_{LIMIT\ VALUEY}$, then the HS-FET turns on. The part does not exit OCP unless I_L _{PEAK} drops below its set limit. If the OCP lasts longer than 150µs, then the buck enters hiccup mode.

System Control Signals PWRON Functions

PWRON is an input pin to that generates a startup or shutdown event. This pin can be configured to detect a level or a falling edge via the MTP.

If the PWRON MODE bit is set to 1, then the PWRON_DEBOUNCE_TIMER_bit can set the PWRON pin's debounce timer to filter mechanical switch short-press noise.

If the PWRON MODE bit is set to 0, then PWRON operates as an enable (EN) pin. Pull PWRON high to turn the PMIC on; pull PWRON low to turn it off.

PWRON_MODE = 1 (Edge Trigger)

Start-Up

The start-up sequence begins once V_{AVIN} exceeds its UVLO threshold and PWRON is pulled low for longer than PWRON_DEBOUNCE_TIMER_while the PMIC is off. Once the start-up sequence is complete, then the PWRON detection function can be enabled.

Shutdown

The shutdown sequence begins once PWRON is pulled low for longer than PWRON_DEBOUNCE_TIMER_while the PMIC is on. The MP5424 turns off all of the bucks, LDOs, and load switch. The shutdown sequence can be configured via the MTP e-fuse.

If the PWRON pin remains low after the shutdown sequence is complete, then the MP5424 remains in the shutdown state. If the PWRON pin is pulled high after the shutdown sequence is complete, then the MP5424 continues the shutdown sequence.

Figure 9: PWRON_MODE = 1 (Press PWRON to Shutdown)

PWRON_MODE = 0 (Level Trigger)

The PMIC enters the start-up sequence once V_{AVIN} exceeds its UVLO threshold and PWRON is pulled high.

If PWRON is pulled low while the MP5424 is on, then the device executes the shutdown sequence. If PWRON is pulled high while the MP5424 is off, then the MP5424 executes a start-up sequence. During a start-up or shutdown sequence, the PWRON pin function is blanked until the sequence is complete. For example, if PWRON is high during a shutdown sequence and then the PMIC finishes the shutdown sequence, the PMIC executes the start-up sequence (see Figure 10).

Figure 10: PWRON Enable and Disable Function

EN1 Functions

EN1 is a multi-function pin. The LSWO pin and LDO 2 can be selected as EN1's input according to the EN1_SELECT bit of CLT3 register. EN EN1 Pin bit can enable/ disable EN1 functions. EN1_INV defines EN1 as active high or active low.

The EN1 pin can be used to control the power rails' start-up and shutdown sequences. This is useful for non-l²C interface applications.

Figure 11 on page 23 shows the EN1 function. If EN1 INV is high and EN1 controls buck 2 and buck 3, then buck 2 and buck 3 turn off sequentially when EN1 is pulled low. If EN1 is pulled high, buck 2 and buck 3 turn on sequentially. PWRON has a higher priority than EN1, so if PWRON is pulled low, then all of the power rails enter the shutdown sequence. The buck, LDO, and load switch enable/disable functions are controlled via the PWRON and EN1 pins.

Figure 11: EN1 Function

Thermal Warning and Shutdown

Thermal warning and thermal shutdown prevent the part from operating at exceedingly high temperatures. If the silicon die temperature exceeds 120°C, then the MP5424 sets the OTWARNING bit to 1.

If the die temperature exceeds 153°C, then the MP5424 sets the OTEMPP bit to 1 and the system enters the shutdown sequence. Once the temperature drops to 130°C, the system enters the start-up sequence.

I ²C Timing

The PMIC's I²C interface is powered by an internal, fixed, 2V power supply. If V_{INX} exceeds its UVLO threshold during a start-up through VIN, then the 2V LDO power supply is ready. The I^2C function is disabled during the start-up sequence. Once the start-up sequence is complete for all enabled power rails, the I^2C function is available (see Figure 12).

If the I ²C is not used, SCL and SDA should be pulled high via a resistor.

Figure 12: I²C Timing Diagram

I ²C INTERFACE

I ²C Serial Interface Description

The 1^2C is a two-wire, bidirectional serial interface consisting of a data line (SDA) and a clock line (SCL). These lines are pulled up externally to a bus voltage (V_{BUS}) when idle. A master device is connected to the line. The master generates the SCL signal and device address, and arranges the communication sequence.

The MP5424 interface is an I^2C slave that can support fast mode (400kHz) and high-speed mode (3.4Mhz). The I^2C interface adds flexibility to the power supply solution. Among other parameters, V_{OUT} and the transition slew rate can be controlled via the ²C interface. If the master sends the address as an 8-bit value, then the 7 bit address should be followed by a 0 to indicate a read (R) operation or 1 to indicate a write (W) operation.

Start and Stop Conditions

The start (S) and stop (P) conditions are signaled by the master device, and signify the beginning and the end of an I ²C transfer. The start condition is defined as the SDA signal transitioning from high to low while SCL is high. The stop condition is defined as the SDA signal transitioning from low to high while SCL is high (see Figure 13).

Figure 13: Start (S) and Stop (P) Conditions

The master then generates the SCL clocks, and transmits the device address and the read/write direction bit (R/W) on the SDA line.

Transfer Data

Data is transferred in 8-bit bytes via the SDA line. Each byte of data should be followed by an acknowledge (ACK) bit.

I ²C Update Sequence

The MP5424 requires a start condition, a valid $I²C$ address, a register address byte, and a data byte for a single data update. After receiving each byte, the MP5424 acknowledges the byte by pulling the SDA line low during the high period of a single clock pulse. A valid I^2C address selects the MP5424. The MP5424 performs an update on the falling edge of the LSB byte. Figure 14, Figure 15, and Figure 16 show examples of I²C write and read sequences.

Figure 16: Read Single Register

REGISTER DESCRIPTION

MTP E-Fuse Configuration Table

MTP E-Fuse Description

Table 1: Output Reference Voltage Chart (BUCK1_VID = 0, Buck2_VID = 0, Buck3_VID = 0)

MP5424 – 5V POWER MANAGEMENT IC WITH I²C AND MTP

MP5424 – 5V POWER MANAGEMENT IC WITH I²C AND MTP

I ²C Bus Slave Address

The slave address is a 7-bit address followed by an 8th read or write (R/W) data direction bit. The A5, A4, A3, A2, and A1 bits can be configured via the MTP e-fuse.

Notes:

15) This bit is configurable via the MTP e-fuse.

16) The slave address is 0x69 (A[7:1] = 1101 001) by default.

I ²C REGISTER MAP

Notes:

17) The I²C bits do not control the real circuitry. Only the MTP bits control those functions. The MTP value only reloads the circuitry when the PWRON pin turns off, the MTP is configured, or AVIN > UVLO threshold.

18) Reserved bits must be written to 0.

Register Description

PRELIMINARY SPECIFICATIONS SUBJECT TO CHANGE

Most of the register bits share the same description as the MTP e-fuse configuration table on page 26. Table 2 shows the descriptions of the I²C register bits that are different from the MTP register bits.

The I²C register's default values are determined by the MTP table.

The I²C register can be reset to the hard-coded default values under two conditions:

- 1. There is a CRC error while loading the MTP.
- 2. The MTP page is set to 0.

Thermal shutdown does not reset the I²C register.

Table 2: I²C Register Descriptions

APPLICATION INFORMATION

Selecting the Inductor

AMMPL Optimized Performance with MPS Inductor MPL-AL6050 Series

For most applications, use a 0.47µH to 2.2µH inductor with a DC current rating at least 25% greater than the maximum load current $(I_{LOAD MAX})$. For improved efficiency, use an inductor with a DC resistance below 15mΩ. For most designs, the inductance (L_1) can be calculated with Equation (1):

$$
L_1 = \frac{V_{\text{OUT}} \times (V_{\text{IN}} - V_{\text{OUT}})}{V_{\text{IN}} \times \Delta I_L \times f_{\text{osc}}}
$$
(1)

Where ∆I_L is the inductor ripple current.

Choose the inductor ripple current to be approximately 30% of $I_{\text{LOAD MAX}}$. The maximum inductor peak current (IL(MAX)) can be estimated with Equation (2):

$$
I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}
$$
 (2)

Choose an inductor with a higher inductance to improve efficiency under light-load conditions $(<100mA)$.

MPS inductors are optimized and tested for use with our complete line of integrated circuits. Table 3 lists MPS's power inductor recommendations for use with the MP5424. Select a part number based on your design requirements.

Visit MonolithicPower.com under Products > Inductors for more information.

Selecting the Step-Down Converter Input Capacitor (C1)

The step-down converter has a discontinuous input current (I_{IN}) , and requires a capacitor to supply the AC current to the converter while maintaining the DC V_{IN} . Use low-ESR capacitors for the best performance. Ceramic capacitors

with X5R or X7R dielectrics are recommended due to their low ESR and small temperature coefficients. For most applications, a 22µF capacitor is sufficient.

Since the input capacitor (C1) absorbs the input switching current, it requires an adequate ripple current rating. The RMS current in C_1 (I_{C_1}) can be estimated with Equation (3):

$$
I_{C1} = I_{LOAD} \times \sqrt{\frac{V_{OUT}}{V_{IN}} \left(1 - \frac{V_{OUT}}{V_{IN}}\right)}\tag{3}
$$

The worst-case condition occurs at $V_{IN} = 2 \times V_{OUT}$, which can be estimated with Equation (4):

$$
I_{C1} = \frac{I_{LOAD}}{2} \tag{4}
$$

For simplification, choose C1 to have an RMS current rating greater than half of $I_{\text{LOAD MAX}}$.

C1 can be electrolytic, tantalum, or ceramic. If using electrolytic or tantalum capacitors, add a small, high-quality ceramic capacitor (0.1μF) placed as close to the IC as possible. If using ceramic capacitors, ensure that they have enough capacitance to provide sufficient charge to prevent excessive voltage ripple at the input. The input voltage ripple (ΔV_{IN}) caused by the capacitance can be calculated with Equation (5):

$$
\Delta V_{IN} = \frac{I_{LOAD}}{f_{SW} \times C1} \times \frac{V_{OUT}}{V_{IN}} \times \left(1 - \frac{V_{OUT}}{V_{IN}}\right) \tag{5}
$$

Selecting the Step-Down Converter Output Capacitor (C2)

The output capacitor (C2) for the step-down converter maintains the DC V_{OUT} . C2 can be ceramic, tantalum, or electrolytic. For the best results, use low-ESR capacitors to keep the output voltage ripple (ΔV_{OUT}) low. For most applications, two 22µF ceramic capacitors are sufficient .

 ΔV_{OUT} can be estimated with Equation (6):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{SW}} \times L_1} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times \left(R_{\text{ESR}} + \frac{1}{8 \times f_{\text{SW}} \times C2}\right) (6)
$$

Where R_{ESR} is the equivalent series resistance (ESR) value of C2.

For ceramic capacitors, the capacitance dominates the impedance at f_{SW} , and causes the majority of ΔV_{OUT} . For simplification, ΔV_{OUT} can be calculated with Equation (7):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{8 \times f_{\text{SW}}^2 \times L_1 \times C2} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \tag{7}
$$

For tantalum or electrolytic capacitors, the ESR dominates the impedance at f_{SW} .

For simplification, ΔV_{OUT} be estimated with Equation (8):

$$
\Delta V_{\text{OUT}} = \frac{V_{\text{OUT}}}{f_{\text{SW}} \times L_1} \times \left(1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}\right) \times R_{\text{ESR}} \tag{8}
$$

The characteristics of C2 also affect the system stability.

Table 4 lists the recommended components for MP5424.

Table 4: Recommended External Components for DC/DC Converters and LDOs

PCB Layout Guidelines (19)

Efficient PCB layout is critical for stable operation. It is recommended to use a 4-layer board for improved performance. For the best results, refer to Figure 17 and follow the guidelines below:

- 1. Connect the input ground to the GNDx pin using short and wide traces.
- 2. Connect the input capacitor to the VINx pin using short and wide traces.
- 3. Ensure FB1, FB2, FB3, and FB4 are Kelvinconnected to the buck 1, buck 2, buck 3, and buck 4 output capacitors. Do not connect FB directly to the inductor's output node.
- 4. Route SW away from sensitive analog areas, such as FB1, FB2, FB3, and FB4.

Figure 17: Recommended PCB Layout (20)

Notes:

19) The recommended PCB layout is based on Figure 18 on page 40.

20) It is recommended to separate buck 1's PGND and buck 3's PGND from buck 2's PGND and buck 4's PGND on the top layer.

TYPICAL APPLICATION CIRCUITS

Figure 18: Typical Application Circuit (21) (22)

TYPICAL APPLICATION CIRCUITS *(continued)*

Figure 19: Typical Application Circuit (with Buck 1 and Buck 3 in Parallel) (21) (22)

Notes:

- 21) VIN5's minimum V_{IN} is equal to the maximum nominal V_{OUT} of LDO 4 and LDO 5. Connect the VIN5 and VIN1 pins if LDO 4 and LDO 5 are not used.
- 22) If operating at a 2.2MHz f_{SW} and with a small duty cycle, ensure that the buck's on time is >100ns for increased system stability.

PACKAGE INFORMATION MF-PO-D-0426 revision 0.0

QFN-26 (3.5mmx4.5mm)

TOP VIEW

SIDE VIEW

BOTTOM VIEW

RECOMMENDED LAND PATTERN

NOTE:

1) LAND PATTERNS OF PIN1,9,14,22 HAVE THE SAME LENGTH AND WIDTH. 2)ALL DIMENSIONS ARE IN MILLIMETERS. 3) LEAD COPLANARITY SHALL BE 0.08 MILLIMETERS MAX. 4) JEDEC REFERENCE IS MO-220. 5) DRAWING IS NOT TO SCALE.

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CARRIER INFORMATION

